

# 4V Drive Pch MOSFET

## TT8J2

### ●Structure

Silicon P-channel MOSFET

### ●Features

- 1) Low On-resistance.
- 2) High Power Package.
- 3) Low voltage drive. (4V)

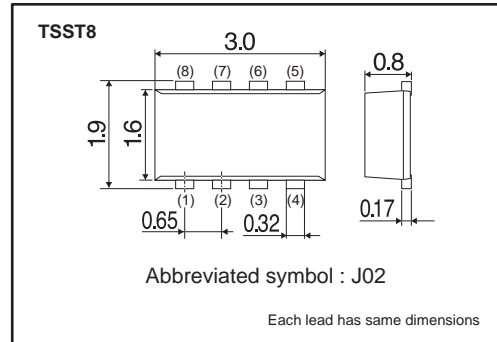
### ●Applications

Switching

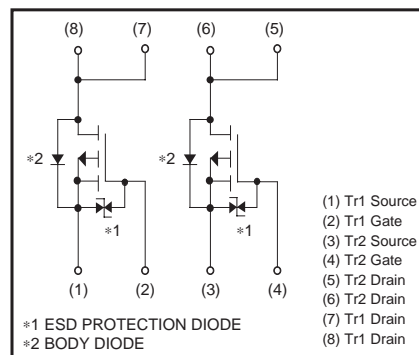
### ●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
TT8J2		○

### ●Dimensions (Unit : mm)



### ●Inner circuit



### ●Absolute maximum ratings (Ta=25°C)

<It is the same ratings for the Tr1 and Tr2.>

Parameter	Symbol	Limits	Unit	
Drain-source voltage	$V_{DS}$	-30	V	
Gate-source voltage	$V_{GS}$	±20	V	
Drain current	Continuous	$I_D$	±2.5	A
	Pulsed	$I_{DP}$ *1	±10	A
Source current (Body diode)	Continuous	$I_S$	-0.8	A
	Pulsed	$I_{SP}$ *1	-10	A
Total power dissipation	$P_D$ *2	1.25	W / TOTAL	
		1.0	W / ELEMENT	
Channel temperature	$T_{ch}$	150	°C	
Range of Storage temperature	$T_{stg}$	-55 to +150	°C	

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 When mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th(ch-a)}$ *	100	°C / W / TOTAL
		125	°C / W / ELEMENT

\* Mounted on a ceramic board

### ●Electrical characteristics (Ta=25°C)

<It is the same characteristics for the Tr1 and Tr2.>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-30	-	-	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	-1.0	-	-2.5	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	-	60	84	mΩ	I <sub>D</sub> = -2.5A, V <sub>GS</sub> = -10V
		-	95	130	mΩ	I <sub>D</sub> = -1.2A, V <sub>GS</sub> = -4.5V
		-	115	160	mΩ	I <sub>D</sub> = -1.2A, V <sub>GS</sub> = -4V
Forward transfer admittance	Y <sub>fs</sub>   *	1.8	-	-	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -2.5A
Input capacitance	C <sub>iss</sub>	-	460	-	pF	V <sub>DS</sub> = -10V
Output capacitance	C <sub>oss</sub>	-	65	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	40	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	7	-	ns	V <sub>DD</sub> ≐ -15V
Rise time	t <sub>r</sub> *	-	20	-	ns	V <sub>GS</sub> = -10V I <sub>D</sub> = -1.2A
Turn-off delay time	t <sub>d(off)</sub> *	-	35	-	ns	R <sub>L</sub> ≐ 12.5Ω
Fall time	t <sub>f</sub> *	-	14	-	ns	R <sub>G</sub> =10Ω
Total gate charge	Q <sub>g</sub> *	-	4.8	-	nC	V <sub>DD</sub> ≐ -15V V <sub>GS</sub> = -5V
Gate-source charge	Q <sub>gs</sub> *	-	1.8	-	nC	I <sub>D</sub> = -2.5A
Gate-drain charge	Q <sub>gd</sub> *	-	1.2	-	nC	R <sub>L</sub> ≐ 6Ω / R <sub>G</sub> =10Ω

\*Pulsed

### ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	-1.2	V	I <sub>S</sub> = -2.5A, V <sub>GS</sub> =0V

\* Pulsed

●Electrical characteristic curves

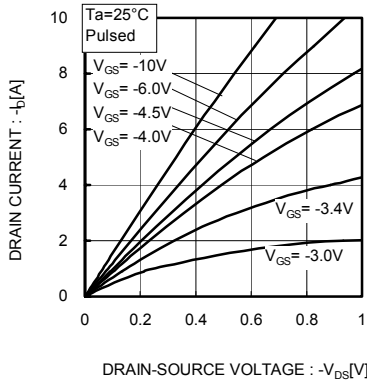


Fig.1 Typical Output Characteristics ( I )

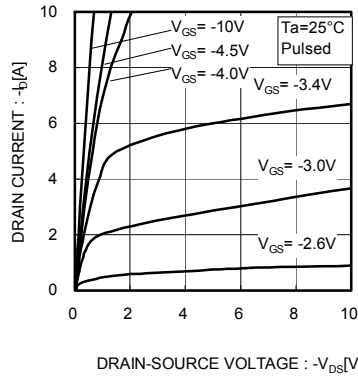


Fig.2 Typical Output Characteristics ( II )

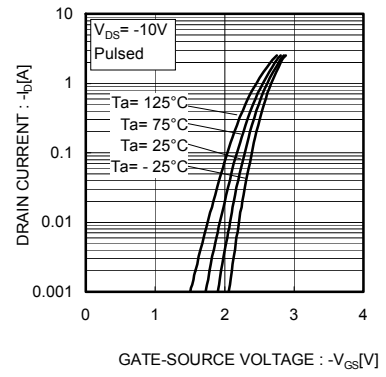


Fig.3 Typical Transfer Characteristics

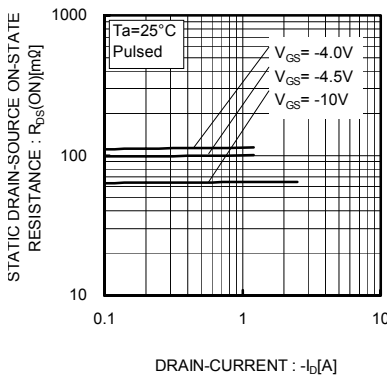


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current ( I )

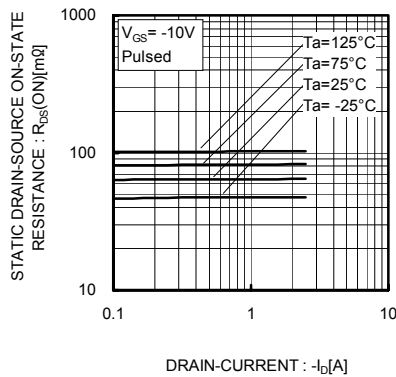


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current ( II )

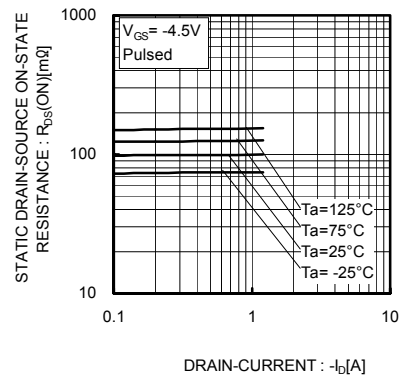


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current ( III )

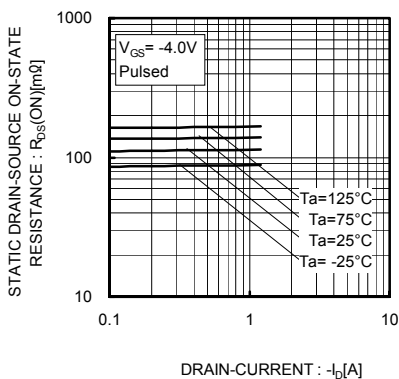


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current ( IV )

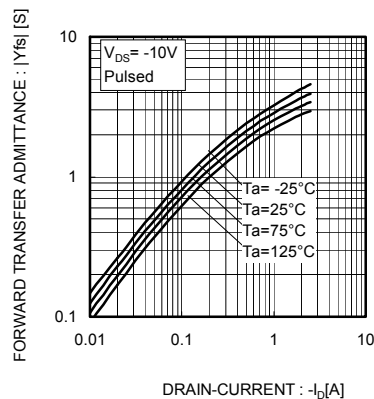


Fig.8 Forward Transfer Admittance vs. Drain Current

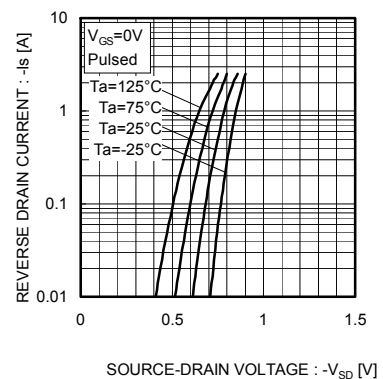


Fig.9 Reverse Drain Current vs. Source-Drain Voltage

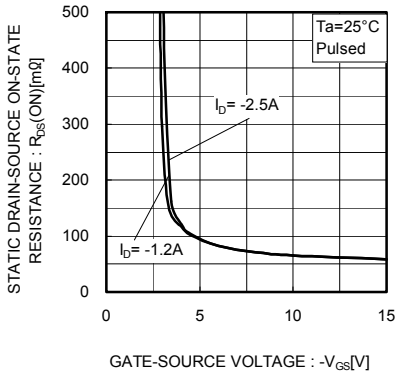


Fig.10 Static Drain-Source On-State Resistance vs. Gate Source Voltage

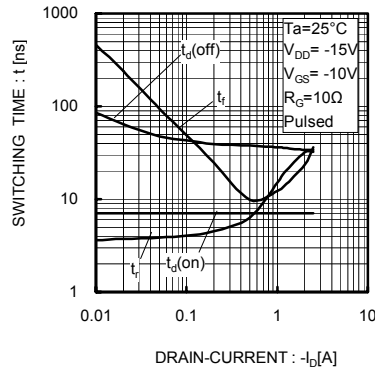


Fig.11 Switching Characteristics

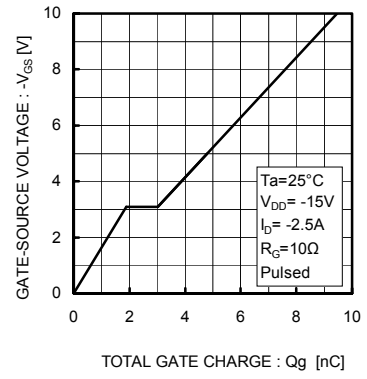


Fig.12 Dynamic Input Characteristics

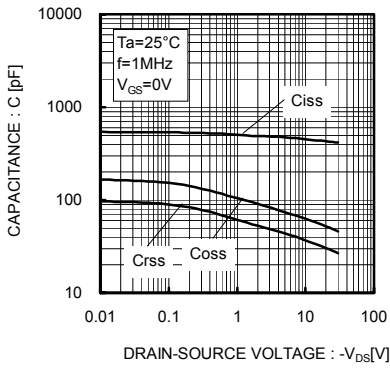


Fig.13 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuits

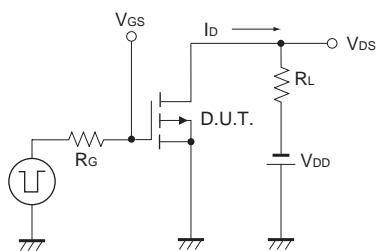


Fig.1-1 Switching Time Measurement Circuit

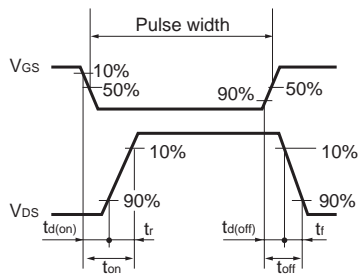


Fig.1-2 Switching Waveforms

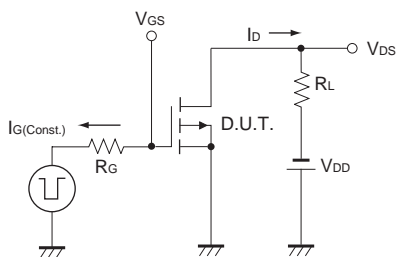


Fig.2-1 Gate Charge Measurement Circuit

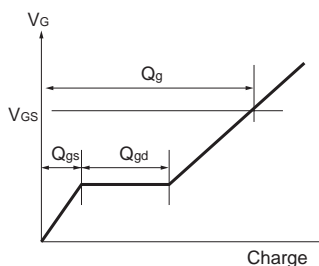


Fig.2-2 Gate Charge Waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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